TUTORIALS

BIREN N. AGARWALA, CHAIR

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TABLE OF CONTENTS

Topic 1. FLIP-CHIP INTERCONNECTIONS

Karl Puttlitz, Sr., Paul Totta, IBM, Hopewell Junction, NY 1

Topic 2. THIN-FILM ELECTROMIGRATION

Anthony Oates, AT&T Bell Laboratories, Allentown, PA 2

Topic 3. PHOTON, ELECTRON, ION AND SCANNING PROBES FOR ADVANCED SEMICONDUCTOR ANALYSES

Robert Hance, Rama Hedge, Vidya Kaushik, Charles Miller, Ronald Pyle, Motorola, Austin, TX 3

Topic 4. RELIABILITY/PROCESSING CHALLENGES FOR ULSI DEVICES

Tak Ning, IBM Research Div., Yorktown Heights, NY 4a

Dave Burnett, Motorola, Austin, TX 4b

Topic 5. PLASTIC PACKAGES — DESIGN AND RELIABILITY

Luu Nguyen, National Semiconductor, Santa Clara, CA 5a

Billy Livesay, Livesay Scientific Services, Rosewell, GA 5b

Topic 6. RELIABILITY ASPECTS OF OPTICAL FIBRE SYSTEM AND NETWORKS

Peter Cochrane, David Heatley, BT Laboratories, Ipswich, UK 6

Topic 7. INTEGRATED CIRCUIT DAMAGE DUE TO ELECTRICAL STRESS

Charvaka Duvvury, Texas Instruments, Dallas, TX 7a

Chenming Hu, UC at Berkeley, Berkeley, CA 7b

Graham Hills, Applied Materials, Santa Clara, CA 7c

Topic 8. RELIABILITY/PROCESSING CHALLENGES FOR ULSI METALLIZATION

Joe McPherson, Texas Instruments, Dallas, TX 8